

Abstract

WIRE BONDING METHODS AND BONDING FORCE CALIBRATION

A method of applying bonding energy to form a bond between a portion of a wire and a contact of a bonding location using a wire bonding machine is provided. The method includes: (1) moving a bonding tool towards the contact; (2) detecting when a portion of the contact (100a) is pressed against a device supporting surface (112) of the wire bonding machine; and (3) applying bonding energy to the portion of the contact such that a bond is formed between the contact and the portion of wire.

Fig. 1B